

### **General Description**

The MAX4719 low-voltage, low on-resistance (RON), dual single-pole/double throw (SPDT) analog switch operates from a single +1.8V to +5.5V supply. The MAX4719 features  $20\Omega$  R<sub>ON</sub> (max) with  $1.2\Omega$  flatness and  $0.4\Omega$  matching between channels. The switch offers break-before-make switching (1ns) with ton <80ns and tOFF <40ns at +2.7V. The digital logic inputs are +1.8V logic compatible with a +2.7V to +3.6V supply.

The switch is packaged in a chip-scale package (UCSP™), significantly reducing the required PC board area. The chip occupies only a 2.0mm x 1.50mm area and has a 4 x 3 bump array with a bump pitch of 0.5mm. The MAX4719 is also available in a 10-pin µMAX package.

### **Applications**

Cell Phones

Battery-Operated Equipment Audio/Video-Signal Routing Low-Voltage Data-Acquisition Systems Sample-and-Hold Circuits **PDAs** 

UCSP is a trademark of Maxim Integrated Products, Inc. Rail-to-Rail is a registered trademark of Nippon Motorola, Ltd.

#### Features

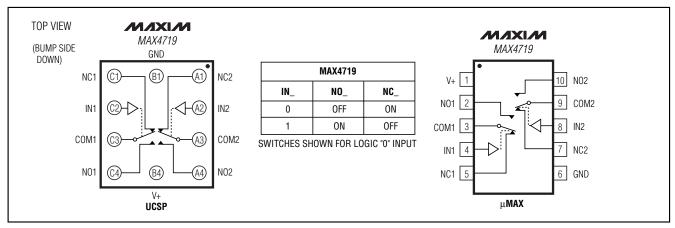
- ◆ -3dB Bandwidth: >300MHz
- ♦ Low 15pF On-Channel Capacitance
- ♦ Single-Supply Operation from +1.8V to +5.5V
- ♦ 20Ω Ron (max) Switch  $0.4\Omega$  (max) Ron Match (+3.0V Supply) 1.2 $\Omega$  (max) Ron Flatness (+3.0V Supply)
- ♦ Rail-to-Rail® Signal Handling
- ♦ High Off-Isolation: -55dB (10MHz)
- ♦ Low Crosstalk: -80dB (10MHz)
- ♦ Low Distortion: 0.03%
- ♦ +1.8V CMOS-Logic Compatible
- ♦ <0.5nA Leakage Current at +25°C
  </p>

#### **Ordering Information**

PART	TEMP RANGE	PIN/BUMP- PACKAGE	TOP MARK
MAX4719EUB	-40°C to +85°C	10 μMAX	_
MAX4719EBC-T*	-40°C to +85°C	12 UCSP-12	ABJ

Note: UCSP package requires special solder temperature profile described in the Absolute Maximum Ratings section.

### Pin Configurations/Functional Diagrams/Truth Table



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<sup>\*</sup>UCSP reliability is integrally linked to the user's assembly methods, circuit board material, and environment. See the UCSP reliability notice in the UCSP Reliability section of this data sheet for more information.

#### **ABSOLUTE MAXIMUM RATINGS**

(All Voltages Referenced to GND)	ESD Method 3015.7	2kV
V+, IN0.3V to +6.0V	Operating Temperature Range	40°C to +85°C
COM_, NO_, NC_ (Note 1)0.3V to (V+ + 0.3V)	Junction Temperature	+150°C
Continuous Current COM_, NO_, NC±100mA	Storage Temperature Range	65°C to +150°C
Peak Current COM_, NO_, NC_	Lead Temperature (soldering, 10s)	+300°C
(pulsed at 1ms, 10% duty cycle)±200mA	Bump Temperature (soldering) (Note 2)	
Continuous Power Dissipation (T <sub>A</sub> = +70°C)	Infrared (15s)	+220°C
10-Pin µMAX (derate 5.6mW/°C above +70°C)444mW	Vapor Phase (60s)	+215°C
12-Bump UCSP (derate 11.4mW/°C above +70°C)909mW		

- Note 1: Signals on COM\_, NO\_, or NC\_ exceeding V+ or GND are clamped by internal diodes. Limit forward-diode current to maximum current rating.
- Note 2: This device is constructed using a unique set of packaging techniques that impose a limit on the thermal profile the device can be exposed to during board level solder attach and rework. This limit permits only the use of the solder profiles recommended in the industry standard specification, JEDEC 020A, paragraph 7.6, table 3 for IR/VPR and convection reflow. Preheating is required. Hand or wave soldering is not allowed.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

#### **ELECTRICAL CHARACTERISTICS—Single +3V Supply**

 $(V+=+2.7V \text{ to } +3.6V, V_{IH}=+1.4V, V_{IL}=+0.5V, T_A=T_{MIN} \text{ to } T_{MAX}, \text{ unless otherwise noted. Typical values are at } V+=+3.0V, T_A=+25^{\circ}C, \text{ unless otherwise noted.)}$  (Notes 3, 4)

PARAMETER	SYMBOL	CONDITIONS	TA	MIN	TYP	MAX	UNITS	
Analog Signal Range	V <sub>COM</sub> _, V <sub>NO</sub> _, V <sub>NC</sub> _		T <sub>MIN</sub> to T <sub>MAX</sub>	0		V+	V	
ANALOG SWITCH								
		V 0.7V L 10mA	+25°C		14	20		
On-Resistance (Note 5)	Ron	V+ = 2.7V, I <sub>COM</sub> = 10mA; V <sub>NO</sub> or V <sub>NC</sub> = 1.5V	T <sub>MIN</sub> to			25	Ω	
0.5		V 0.7V   40 A	+25°C		0.15	0.4		
On-Resistance Match Between Channels (Notes 5, 6) ΔRON		V+ = 2.7V, I <sub>COM</sub> = 10mA; V <sub>NO</sub> or V <sub>NC</sub> = 1.5V	T <sub>MIN</sub> to T <sub>MAX</sub>			0.5	Ω	
0.5	R <sub>FLAT</sub> (ON)	V+ = 2.7V, I <sub>COM</sub> = 10mA; V <sub>NO</sub> or V <sub>NC</sub> = 1.0V, 1.5V, 2.0V	+25°C		0.6	1.2		
On-Resistance Flatness (Note 7)			T <sub>MIN</sub> to			1.5	Ω	
NO NO OTILLO		V 0.0V V 0.0V 0.0V	+25°C	-0.5	0.01	+0.5		
		_(OFF), V+ = 3.6V, V <sub>COM</sub> = 0.3V, 3.3V; L_(OFF) V <sub>NO</sub> or V <sub>NC</sub> = 3.3V, 0.3V		-1		+1	nA	
		$V + = 3.6V, V_{COM} = 0.3V, 3.3V;$	+25°C	-1	0.01	+1		
COM_ On-Leakage Current Note 8)  ICOM_(ON)		$V_{NO}$ or $V_{NC}$ = 0.3V, 3.3V, or floating	T <sub>MIN</sub> to T <sub>MAX</sub>	-2		+2	nA	
DYNAMIC CHARACTERISTICS								
	TON.	V V 1.5V	+25°C		40	80		
Turn-On Time		$V_{NO\_}$ , $V_{NC\_}$ = 1.5V; $R_L$ = 300 $\Omega$ , $C_L$ = 35pF, Figure 1	T <sub>MIN</sub> to T <sub>MAX</sub>			100	ns	

### **ELECTRICAL CHARACTERISTICS—Single +3V Supply (continued)**

 $(V+ = +2.7V \text{ to } +3.6V, V_{IH} = +1.4V, V_{IL} = +0.5V, T_A = T_{MIN} \text{ to } T_{MAX}, \text{ unless otherwise noted.}$  Typical values are at  $V+ = +3.0V, T_A = +25^{\circ}C$ , unless otherwise noted.) (Notes 3, 4)

PARAMETER	SYMBOL	CONDITIONS	TA	MIN	TYP	MAX	UNITS
		V V 45V	+25°C		20	40	
Turn-Off Time	toff	$V_{NO\_}$ , $V_{NC\_}$ = 1.5V; $R_L$ = 300 $\Omega$ , $C_L$ = 35pF, Figure 1	T <sub>MIN</sub> to			50	ns
		V V 15V	+25°C		8		
Break-Before-Make Time Delay (Note 8)	t <sub>BBM</sub>	$V_{NO\_}$ , $V_{NC\_}$ = 1.5V; $R_L$ = 300 $\Omega$ , $C_L$ = 35pF, Figure 2	T <sub>MIN</sub> to	1			ns
Charge Injection	Q	$V_{GEN} = 2V$ , $R_{GEN} = 0\Omega$ ; $C_L = 1.0$ nF, Figure 3	+25°C		18		рС
Off Indiation	M.	$f = 10MHz$ ; $V_{NO}$ , $V_{NC}$ = $1V_{P-P}$ ; $R_L = 50\Omega$ , $C_L = 5pF$ , Figure 4	+25°C		-55		٩D
Off-Isolation	V <sub>ISO</sub>	$f = 1MHz$ ; $V_{NO\_}$ , $V_{NC\_} = 1V_{P-P}$ ; $R_L = 50\Omega$ , $C_L = 5pF$ , Figure 4	+25°0		-80		dB
Croostally (Note 0)	Voz	$f = 10MHz$ ; $V_{NO}$ , $V_{NC} = 1V_{P-P}$ ; $R_L = 50\Omega$ , $C_L = 5pF$ , Figure 4			-80		- dB
Crosstalk (Note 9)	Vct	$f = 1MHz$ ; $V_{NO\_}$ , $V_{NC\_} = 1V_{P-P}$ ; $R_L = 50\Omega$ , $C_L = 5pF$ , Figure 4	+25°C		-110		
On-Channel -3dB Bandwidth	BW	Signal = 0dBm, $R_L = 50\Omega$ ; $C_L = 5pF$ , Figure 4	+25°C		300		MHz
Total Harmonic Distortion	THD	$V_{COM} = 2V_{P-P}, R_L = 600\Omega$	+25°C		0.03		%
NO_, NC_ Off-Capacitance	C <sub>NO_(OFF)</sub> C <sub>NC_(OFF)</sub>	f = 1MHz, Figure 5	+25°C		9		pF
Switch On-Capacitance	Con	f = 1MHz, Figure 5	+25°C		20		pF
DIGITAL I/O							
Input Logic High Voltage	V <sub>IH</sub>		T <sub>MIN</sub> to T <sub>MAX</sub>	1.4			V
Input Logic Low Voltage	V <sub>IL</sub>		T <sub>MIN</sub> to			0.5	V
Input Leakage Current	I <sub>IN</sub>	V+ = +3.6V, V <sub>IN</sub> _ = 0V or 5.5V	T <sub>MIN</sub> to	-100		+100	nA
POWER SUPPLY	_						
Power-Supply Range	V+		T <sub>MIN</sub> to	1.8		5.5	V
Supply Current	l+	V+ = +5.5V, V <sub>IN</sub> _ = 0V or V+	T <sub>MIN</sub> to T <sub>MAX</sub>			1	μΑ

### **ELECTRICAL CHARACTERISTICS—Single +5V Supply**

(V+ = +4.2V to +5.5V,  $V_{IH}$  = +2.0V,  $V_{IL}$  = +0.8V,  $T_A$  =  $T_{MIN}$  to  $T_{MAX}$ , unless otherwise noted. Typical values are at V+ = +5.0V,  $T_A$  = +25°C, unless otherwise noted.) (Notes 3, 4)

PARAMETER	SYMBOL	CONDITIONS	TA	MIN	TYP	MAX	UNITS
Analog Signal Range	V <sub>COM_</sub> , V <sub>NO_</sub> , V <sub>NC_</sub>		T <sub>MIN</sub> to	0		V+	V
ANALOG SWITCH							
		V 40V I 40 A	+25°C		12	20	
On-Resistance (Note 5)	Ron	V+ = 4.2V, I <sub>COM</sub> = 10mA; V <sub>NO</sub> or V <sub>NC</sub> = 3.5V	T <sub>MIN</sub> to T <sub>MAX</sub>			25	Ω
0.5		V 40V I 40 A	+25°C		0.15	0.4	
On-Resistance Match Between Channels (Notes 5, 6)	ΔRON	V+ = 4.2V, I <sub>COM</sub> = 10mA; V <sub>NO</sub> or V <sub>NC</sub> = 3.5V	T <sub>MIN</sub> to T <sub>MAX</sub>			0.5	Ω
On Desistance Flatness		V 4.0V I 40A	+25°C		0.4	1	
On-Resistance Flatness (Note 7)	RFLAT(ON)	V+ = 4.2V, I <sub>COM</sub> = 10mA; V <sub>NO</sub> or V <sub>NC</sub> = 1.0V, 2.0V, 4.5V	T <sub>MIN</sub> to T <sub>MAX</sub>			1.2	Ω
NO NO Office de Commont	1	V. 55V.V 10V.45V.	+25°C	-0.5	+0.01	+0.5	
NO_, NC_ Off-Leakage Current (Note 8)	INO_(OFF),	$V_{NO_{-}(OFF)}$ , $V_{NO_{-}}$	-1		+1	nA	
	ICOM_(ON)	$V+ = 5.5V, V_{COM} = 1.0V, 4.5V; V_{NO} \text{ or } V_{NC} = 1.0V, 4.5V, \text{ or } floating$	+25°C	-1	+0.01	+1	nA
COM_ On-Leakage Current (Note 8)			T <sub>MIN</sub> to T <sub>MAX</sub>	-2		+2	
DYNAMIC CHARACTERISTICS							
		V <sub>NO_</sub> , V <sub>NC_</sub> = 3.0V; R <sub>L</sub> = 300Ω, C <sub>L</sub> = 35pF, Figure 1	+25°C		30	80	ns
Turn-On Time	ton		T <sub>MIN</sub> to			100	
			+25°C		20	40	
Turn-Off Time	tOFF	$V_{NO\_}$ , $V_{NC\_}$ = 3.0V; $R_L$ = 300 $\Omega$ , $C_L$ = 35pF, Figure 1	T <sub>MIN</sub> to T <sub>MAX</sub>			50	ns
			+25°C		8		
Break-Before-Make Time Delay (Note 8)	tBBM	$V_{NO\_}$ , $V_{NC\_}$ = 3.0V; $R_L$ = 300 $\Omega$ , $C_L$ = 35pF, Figure 2	T <sub>MIN</sub> to	1			ns
DIGITAL I/O							
Input Logic High Voltage	V <sub>IH</sub>		T <sub>MIN</sub> to T <sub>MAX</sub>	2.0			V
Input Logic Low Voltage	V <sub>IL</sub>		T <sub>MIN</sub> to			0.8	V
Input Leakage Current	I <sub>IN</sub>	V+ = 5.5V, V <sub>IN</sub> _ = 0V or V+	T <sub>MIN</sub> to	-0.1		+0.1	μΑ

\_\_ /N/|X|/VI

#### **ELECTRICAL CHARACTERISTICS—Single +5V Supply (continued)**

 $(V+ = +4.2V \text{ to } +5.5V, V_{IH} = +2.0V, V_{IL} = +0.8V, T_A = T_{MIN} \text{ to } T_{MAX}, \text{ unless otherwise noted. Typical values are at } V+ = +5.0V, T_A = +25^{\circ}C, \text{ unless otherwise noted.})$  (Notes 3, 4)

PARAMETER	SYMBOL	CONDITIONS	TA	MIN	TYP	MAX	UNITS
POWER SUPPLY							
Power-Supply Range	V+		T <sub>MIN</sub> to T <sub>MAX</sub>	1.8		5.5	V
Supply Current	l+	V+ = 5.5V, V <sub>IN</sub> _ = 0V or V+	T <sub>MIN</sub> to			1	μΑ

**Note 3:** UCSP parts are 100% tested at +25°C only, and guaranteed by design over the specified temperature range. μMAX parts are 100% tested at T<sub>MAX</sub> and guaranteed by design over the specified temperature range.

**Note 4:** The algebraic convention used in this data sheet is where the most negative value is a minimum and the most positive value is a maximum.

Note 5: Guaranteed by design for UCSP parts.

**Note 6:**  $\Delta R_{ON} = R_{ON(MAX)} - R_{ON(MIN)}$ .

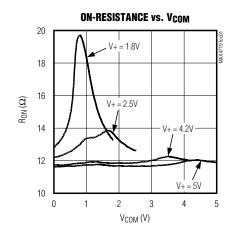
**Note 7:** Flatness is defined as the difference between the maximum and minimum value of on-resistance as measured over the specified analog signal ranges.

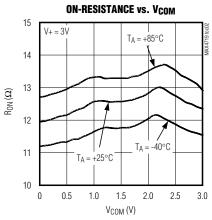
Note 8: Guaranteed by design.

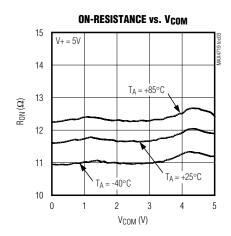
Note 9: Between any two switches.

### \_Typical Operating Characteristics

( $T_A = +25$ °C, unless otherwise noted.)

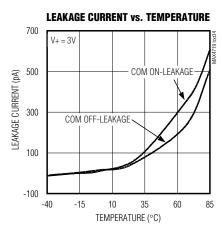


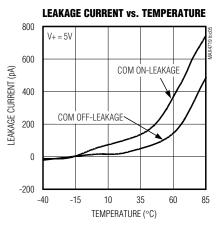


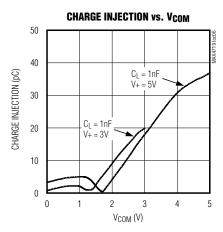


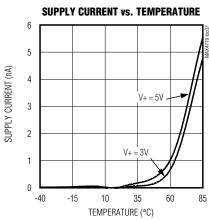
### Typical Operating Characteristics (continued)

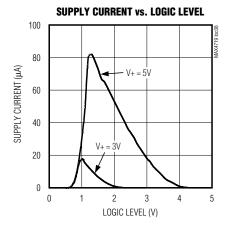
 $(T_A = +25^{\circ}C, \text{ unless otherwise noted.})$ 

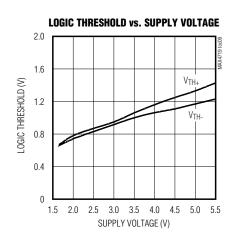


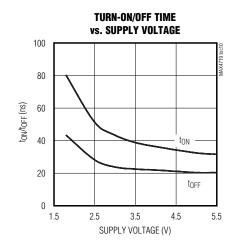






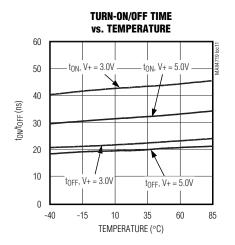


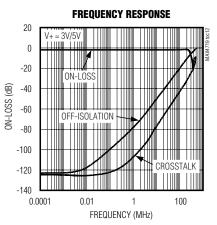


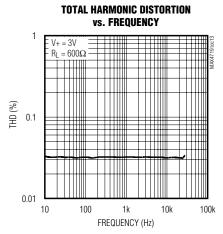


### Typical Operating Characteristics (continued)

 $(T_A = +25^{\circ}C, \text{ unless otherwise noted.})$ 







#### **Pin Description**

Р	IN	NAME	FUNCTION
UCSP	μΜΑΧ	INAIVIE	FONCTION
A1	7	NC2	Analog Switch 2—Normally Closed Terminal
A2	8	IN2	Digital Control Input for Analog Switch 2
АЗ	9	COM2	Analog Switch 2—Common Terminal
A4	10	NO2	Analog Switch 2—Normally Open Terminal
B1	6	GND	Ground
B4	1	V+	Positive-Supply Voltage Input
C1	5	NC1	Analog Switch 1—Normally Closed Terminal
C2	4	IN1	Digital Control Input for Analog Switch 1
C3	3	COM1	Analog Switch 1—Common Terminal
C4	2	NO1	Analog Switch 1—Normally Open Terminal

### Detailed Description

The MAX4719 high-speed, low-voltage,  $20\Omega$  R<sub>ON</sub>, dual SPDT analog switch operates from a single +1.8V to +5.5V supply. The switch features break-before-make switching operation and fast switching speeds (toN = 80ns (max), toff = 40ns (max)).

## \_Applications Information

#### **Digital Control Inputs**

The MAX4719 logic inputs accept up to +5.5V regardless of supply voltage. For example, with a +3.3V supply, IN\_ can be driven low to GND and high to +5.5V allowing for mixing of logic levels in a system. Driving the control logic inputs rail-to-rail minimizes power consumption. For a +3V supply voltage, the logic thresholds are 0.5V (low) and 1.4V (high); for a +5V supply voltage, the logic thresholds are 0.8V (low) and 2.0V (high).

#### **Analog Signal Levels**

The on-resistance of the MAX4719 changes very little for analog input signals across the entire supply voltage range (see the *Typical Operating Characteristics*). The switches are bidirectional, so the NO\_, NC\_, and COM\_ pins can be either inputs or outputs.

#### Power-Supply Sequencing and Overvoltage Protection

Caution: Do not exceed the absolute maximum ratings because stresses beyond the listed ratings may cause permanent damage to the device.

Proper power-supply sequencing is recommended for all CMOS devices. Always apply V+ before applying analog signals, especially if the analog signal is not current-limited.

#### **UCSP Package Considerations**

For general UCSP package information and PC layout considerations, please refer to the Maxim Application Note (Wafer-Level Chip-Scale Package).

#### **UCSP Reliability**

The chip-scale package (UCSP) represents a unique packaging form factor that may not perform equally to a packaged product through traditional mechanical reliability tests. UCSP reliability is integrally linked to the user's assembly methods, circuit board material, and

usage environment. The user should closely review these areas when considering use of a UCSP package. Performance through Operating Life Test and Moisture Resistance remains uncompromised as it is primarily determined by the wafer-fabrication process.

Mechanical stress performance is a greater consideration for a UCSP package. UCSPs are attached through direct solder contact to the user's PC board, foregoing the inherent stress relief of a packaged product lead frame. Solder joint contact integrity must be considered. Information on Maxim's qualification plan, test data, and recommendations are detailed in the UCSP application note, which can be found on Maxim's website at www.maxim-ic.com.

#### **Chip Information**

TRANSISTOR COUNT: 235 PROCESS: BICMOS

#### **Test Circuits/Timing Diagrams**

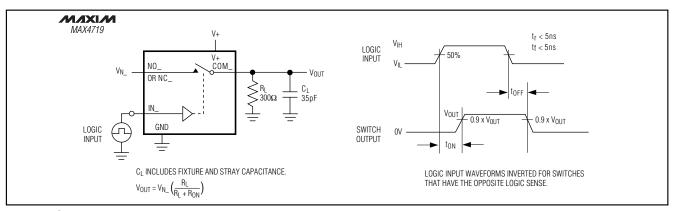


Figure 1. Switching Time

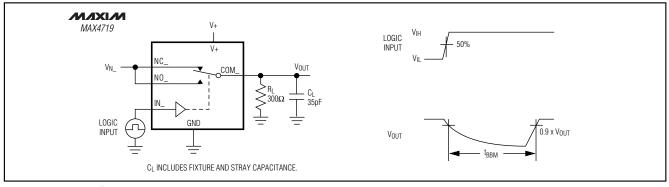


Figure 2. Break-Before-Make Interval

### Test Circuits/Timing Diagrams (continued)

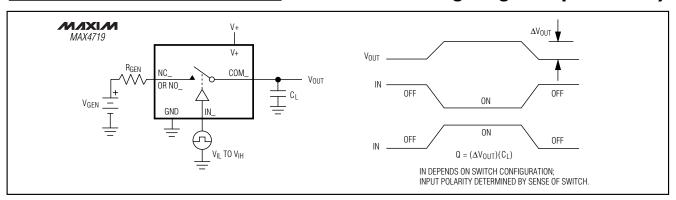


Figure 3. Charge Injection

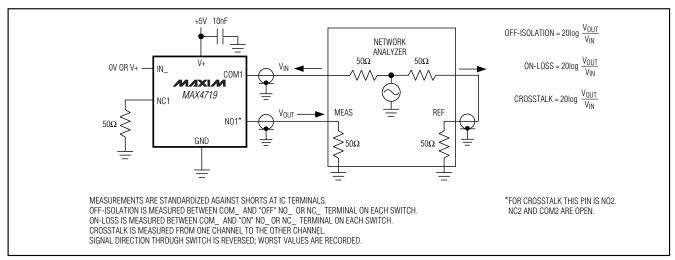


Figure 4. On-Loss, Off-Isolation, and Crosstalk

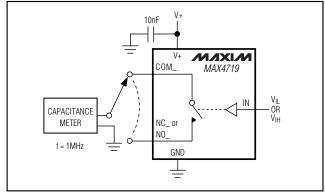


Figure 5. Channel Off/On-Capacitance

### Package Information

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to **www.maxim-ic.com/packages**.)

